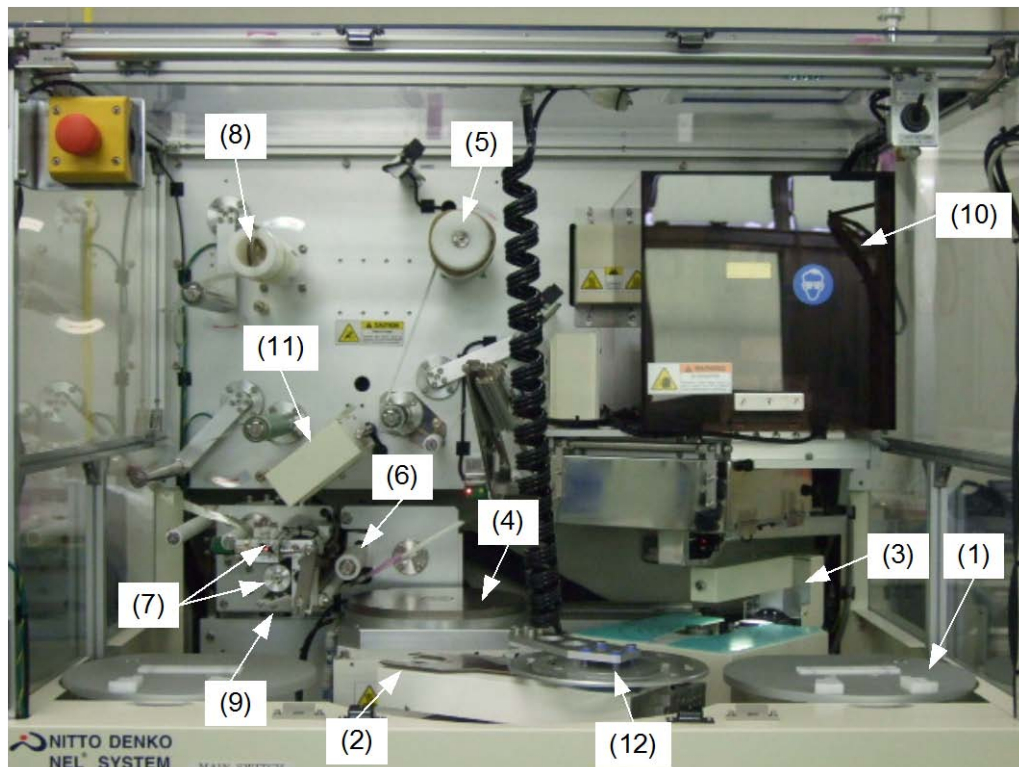


2.2 Function and name of the main parts



- | | |
|--------------------------|---|
| (1) Cassette table: | The right / left table to place a cassette. |
| (2) Robot: | Picks a wafer from the cassette, and transfers the wafer to the aligner and chuck table. After the process has completed, puts the wafer into the cassette. |
| (3) Aligner: | Perform centering and alignment of the wafer. |
| (4) Chuck table: | Vacuum a wafer during peeling the BG tape. |
| (5) Tape delivery shaft: | Delivers peeling tape. |
| (6) Applying roller: | Applies peeling tape onto the wafer applied BG tape on the surface. |
| (7) Peeling roller: | Peels the peeling tape applied on the wafer. |
| (8) Tape winding shaft: | Winds the peeled BG tape with peeling tape. |
| (9) Peeling bar: | Keeps the peeling bar at a fixed angle to disperse the action force onto the wafer surface. Also, it prevents damage of the wafer during peeling process. |
| (10) UV unit* | Irradiates UV ray to reduce the adhesive power of the BG tape. |
| (11) Static eliminator: | Eliminates static electricity of peeling tape and the wafer. |
| (12) Press down plate: | Press the wafer warpage when vacuum error due to warpage of the wafer is occurred. |

(*) Option

2.2 Function and name of the main parts (Continued)

